

**AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A smart label comprising a circuitry pattern and at least one capacitor plate on a smart label substrate, and a structural part comprising an integrated circuit on a chip and at least one capacitor plate on a structural part substrate, the structural part substrate being substantially smaller than the smart label substrate and being attached to the smart label substrate in such a manner that the capacitor plate on the smart label substrate and the capacitor plate on the structural part substrate are aligned thereby electrically connecting the circuitry pattern and the integrated circuit on the chip through a dielectric layer between the capacitor plates wherein the structural part is attached to the smart label substrate on the side opposite to the side where the circuitry pattern is located and the dielectric layer comprises the smart label substrate.

2. (Original) The smart label according to claim 1, wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip.

3. (Original) The smart label according to claim 1, wherein the structural part comprising the integrated circuit on the chip is attached to the smart label by means of a thermoplastic material.

4. (Original) The smart label according to claim 3, wherein the thermoplastic material is an anisotropic conductive thermoplastic film.

5. (Cancel)

6. (Previously Presented) The smart label according to claim 2, wherein the smart label substrate has a dissipation factor of not more than  $0.7 \times 10^{-3}$ .

7. (Previously Presented) The smart label according to claims 1 or 6, wherein the material of the smart label substrate is polyolefin.

8. (Cancel)

9. (Amended) The smart label according to claim 1 or 3 ~~3 or 8~~, wherein the integrated circuit on the chip is located between the thermoplastic material and the smart label substrate.

10. (Previously Presented) The smart label according to claim 1, wherein the material of the structural part substrate is selected from the group consisting of polyimide and polyester.

11. (Currently Amended) A smart label web comprising smart labels one after another and/or side by side, the smart label comprising a circuitry pattern and at least one capacitor plate on a smart label substrate and a structural part comprising an integrated circuit on a chip, and at least one capacitor plate on a structural part substrate, the structural part substrate being substantially smaller than the smart label substrate and being attached to the smart label substrate in such a manner that the capacitor plate on the smart label substrate and the capacitor plate on the structural part substrate are aligned thereby electrically connecting the circuitry pattern and the integrated circuit on the chip through a dielectric layer between the capacitor plates wherein the structural part is attached to the smart label substrate on the same side where the circuitry pattern is located and the dielectric layer comprises a printed isolation layer.

12. (Original) The smart label web according to claim 11, wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip.

13. (Cancel)

14. (Previously Presented) The smart label according to claim 7, wherein the polyolefin is selected from the group consisting of polypropylene and polyethylene.

15. (Currently Amended) A smart label comprising a circuitry pattern on a smart label substrate; and

a structural part, the structural part comprising a thermoplastic film, a base web, and an integrated circuit on a chip on the thermoplastic film, the structural part being attached to the smart label substrate, and the circuitry pattern being electrically connected to the integrated circuit on the chip by at least one capacitor outside the chip, at least one capacitor plate of the at least one capacitor on the smart label substrate opposing at least one capacitor plate of the at least one capacitor on the surface of the base web of the structural part, at least one of the opposing plates being larger than its opposite plate, the structural part smaller than the smart label substrate wherein the integrated circuit on the chip is connected to the circuitry pattern via two capacitors connected in series and located outside the chip and wherein the structural part is attached to the smart label substrate on the side opposite to the side where the circuitry pattern is located, and the dielectric layer comprises the smart label substrate.

16. (Cancel)

17. (Amended) The smart label according to claim ~~16~~ 15, wherein the thermoplastic film material is an anisotropically conductive.

18. (Currently Amended) The smart label according to claim 17, wherein the capacitor comprises capacitor plates which are formed on the smart label substrate and the structural part substrate, the anisotropically conductive thermoplastic film on the same side of the smart label substrate where the circuitry pattern is located and is isolated from ~~the~~ the circuitry ~~patter~~ pattern ~~the smart label substrate forming a dielectric layer between the~~ capacitor plates.

19. (Previously Presented) The smart label according to claim 17, wherein the capacitor comprises capacitor plates which are formed on the smart label substrate and the structural part substrate, the smart label substrate forming a dielectric layer between the capacitor plates.

20. (Amended) The smart label according to claim ~~16~~ 15, wherein the smart label substrate has a dissipation factor of not more than  $0.7 \times 10^{-3}$ .

21. (Amended) The smart label according to claims ~~16~~ 15 or 20, wherein the material of the smart label substrate is polyolefin.

22. (Cancel)

23. (Amended) The smart label according to claims claim 15 ~~16 or 22~~ wherein the structural part comprising the integrated circuit on the chip is attached to the smart label by the thermoplastic film.

24. (Previously Presented) The smart label according to claim 23, wherein the integrated circuit on the chip is located between the thermoplastic material and the smart label substrate.

25. (Amended) The smart label according to claim ~~16~~ 15, wherein the base web of the structural part comprises material selected from the group consisting of polyimide and polyester.